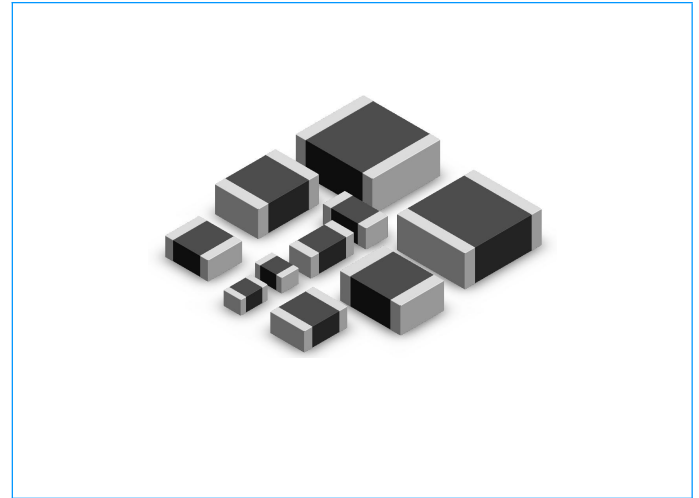


Surface Mount Multilayer Varistor

SV0806H431G0A

Description

The SV0806H431G0A is based on Multilayer fabrication technology. These components are designed to suppress a variety of transient events, including those specified in IEC 61000-4-2 or other standards used for Electromagnetic Compliance (EMC). The SV0806H431G0A is typically applied to protect integrated circuits and other components at the circuit board level. It can operate over a wider temperature range than zener diodes.



Features

- ◆ Rectangle, sizes serialization for hybrid integrated circuit or printed circuit surface mount components
- ◆ There are many side electrode lead-out material, particularly suitable for surface mount technology for solderability and resistance to soldering heat of the stringent requirements
- ◆ Fast response (<1ns)
- ◆ Low leakage current, low clamping voltage
- ◆ Suitable for reflow, wave soldering and hot air hand soldering

Applications

- ◆ Application for Mother Board, Notebook, Cellular Phone, PDA, handheld device, DSC, DV, Scanner, and Set- Top Box...etc.
- ◆ Suitable for Push-Button, Power Line and Low Frequency single line over-voltage protect.

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Electrical Characteristics (25±5°C)

Symbol	Minimum	Typical	Maximum	Units
V_{RMS}	—	—	275	V
V_{DC}	—	—	350	V
V_V	387	—	473	V
V_C	—	—	710	V
I_P	—	—	50	A

V_{RMS} - Maximum AC operating voltage the varistor can maintain and not exceed 30μA leakage current.

V_{DC} - Maximum DC operating voltage the varistor can maintain and not exceed 30μA leakage current.

V_V - Voltage across the device measure at 1mA DC current.

Equivalent to V_{BR} "breakdown voltage".

V_C - Maximum peak current across the varistor with 8/20μs waveform and 1A pulse current.

I_P - Maximum peak current which may be applied with 8/20μs waveform without device failure.

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Shape & Dimensions and Parts & Components

Shape & Dimensions: See Fig.1 and Table 1.

Parts & Components: See Fig.2 and Table 2.

Fig.1

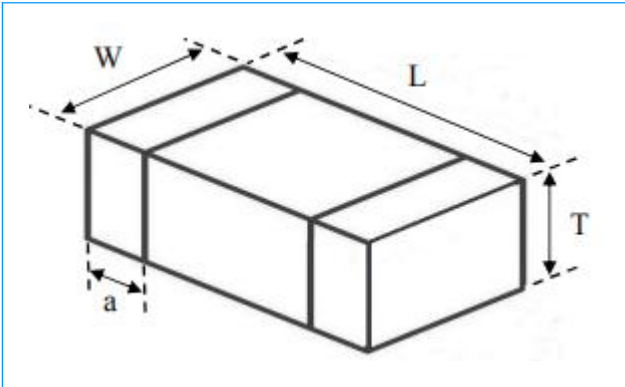


Table 1

Type	L (mm)	W (mm)	T (mm)	a (mm)
0806	2.00±0.25	1.60±0.30	1.90 Max.	0.40±0.20

Fig.2

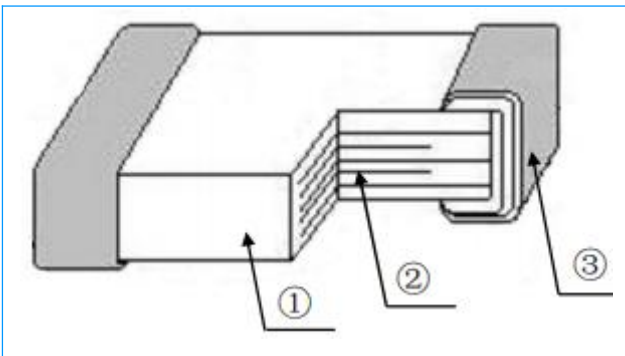


Table 2

Part	①	②	③
Component	ZnO Semiconductor Ceramics for Chip Varistor	Internal Electrode (Ag or Ag-Pd)	Terminal Electrode (Ag/Ni/Sn three layers)

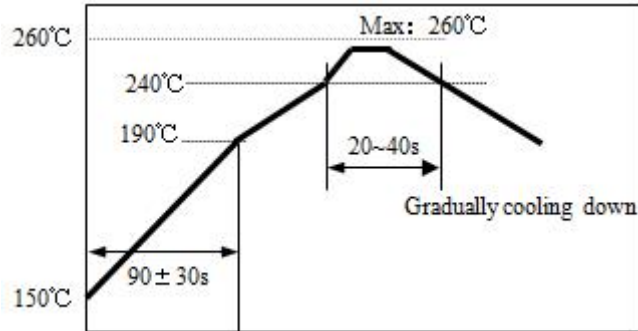
Surface Mount Multilayer Varistor

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Soldering Recommendation

Recommended Soldering Profile

- ◆ Pb Free Solder Paste: Sn/Ag/Cu (96.5/3.0/0.5).
- ◆ Max time at max temp: 10sec.
- ◆ Allowed Reflow time: 2x Max.



Packaging Quantity

Type	Tape	Quantity (pcs/reel)
SV0806H431G0A	Embossed Tape	2000

Notes & Warnings

- ◆ Storage temperature in original packaging: -10~+40°C.
- ◆ Relative Humidity: ≤70%RH.
- ◆ Keep away from corrosive atmosphere and sunlight.
- ◆ Period of Storage: 12 Months.